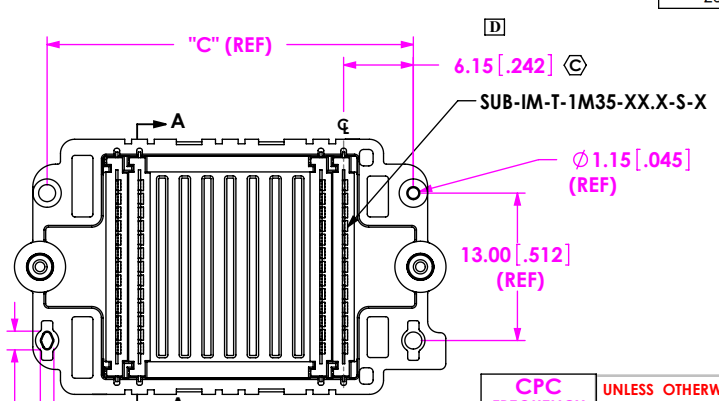
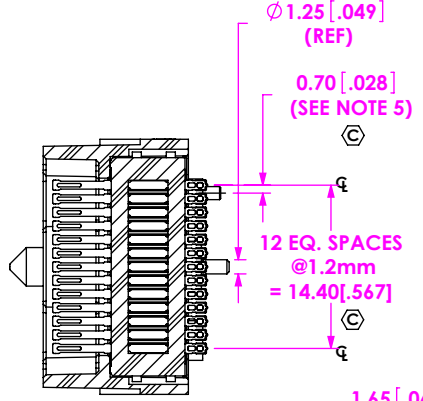
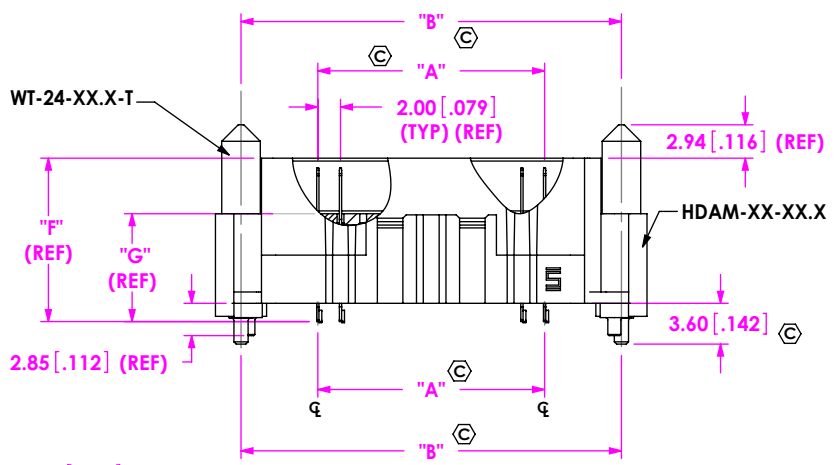
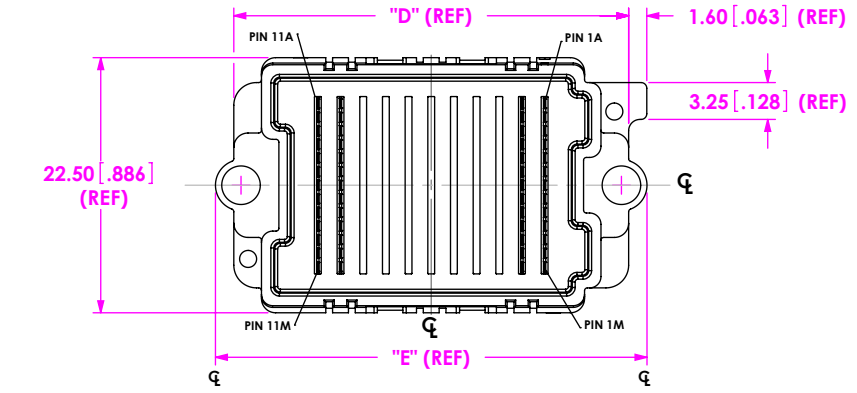


DO NOT SCALE FROM THIS PRINT

DESIGNED & DIMENSIONED IN MILLIMETERS (INCHES FOR REFERENCE ONLY)

HDAM-XX-XX.X-X-13-X-X



No OF POSITIONS
 (13 ROW PER POSITION)
 -11
 -15
 -23

LEAD STYLE
 -12.0: 12MM
 -17.0: 17MM

PLATING SPECIFICATION
 -S: SELECTIVE, .000030 INCHES GOLD IN MATING AREA, MATTE TIN ON TAIL AND GUIDE PINS

OPTION
 -P: PICK & PLACE PAD (USE MPP-26-01-N)

SOLDER CHARGE MATERIAL
 -1: 63%TIN / 37% LEAD
 -2: 95.5% TIN / 3.8% SILVER 0.7% COPPER (LEAD FREE)

No OF ROWS
 -13

TABLE 1

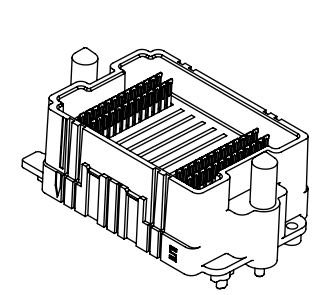
STYLE	"BODY CALLOUT"	"TERMINAL WAFER"	"GUIDE PIN"
-12.0	HDAM-XX-12.0	SUB-IM-T-1M35-12.0-S-X	WT-24-12.0-T
-17.0	HDAM-XX-17.0	SUB-IM-T-1M35-17.0-S-X	WT-24-17.0-T

TABLE 2
STACK HEIGHT

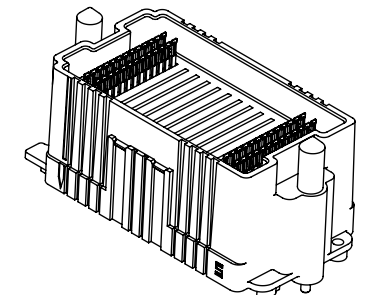
HDAM LEAD STYLE	HDAF LEAD STYLE	
	-08.0	-18.0
-12.0	20.0MM	30.0MM
-17.0	25.0MM	35.0MM

TABLE 3

No. OF POS.	LEAD STYLE	"A"	"B"	"C"	"D"	"E"	"F"	"G"
11	12	20.0 [1.787]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371]	38.06 [1.498]	14.41 [1.567]	9.51 [1.374]
15	12	28.0 [1.102]	41.55 [1.636]	40.30 [1.587]	42.82 [1.688]	46.06 [1.813]	14.41 [1.567]	9.51 [1.374]
23	12	44.0 [1.732]	57.55 [2.266]	56.30 [2.217]	58.82 [2.316]	62.06 [2.493]	14.41 [1.567]	9.51 [1.374]
11	17	20.0 [1.787]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371]	38.06 [1.498]	19.41 [1.764]	14.51 [1.571]
15	17	28.0 [1.102]	41.55 [1.636]	40.30 [1.587]	42.82 [1.688]	46.06 [1.813]	19.41 [1.764]	14.51 [1.571]
23	17	44.0 [1.732]	57.55 [2.266]	56.30 [2.217]	58.82 [2.316]	62.06 [2.443]	19.41 [1.764]	14.51 [1.571]



(-12.0 SHOWN)



(-17.0 SHOWN)

- NOTES:
1. Ⓢ REPRESENTS A CRITICAL DIMENSION.
 2. MINIMUM PUSHOUT FORCE: 2.22N[.5 LB]. FOR WAFERS
 3. CONNECTORS TO BE PACKAGED IN TRAYS.
 4. USE THESE SURFACES TO MEASURE "G" DIMENSION.
 5. DIMENSION FROM Ⓢ OF END TAIL TO Ⓢ OF -A PIN.

FIG 1
 -11: 1T POSITION
 (HDAM-11-12.0-X-13-X-X SHOWN)
 (SOME WAFERS NOT SHOWN FOR CLARITY)

CPC FREQUENCY THIS SHEET

A	C1, C2, C3, C4, C5, C6, C7, C8
B	
C	
D	

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS [INCHES].

TOLERANCES ARE:
 DECIMALS ANGLES
 .X: ±0.3 [0.1]
 .XX: ±0.13 [0.05]
 .XXX: ±0.051 [0.020]

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MATERIAL: DO NOT SCALE DRAWING SHEET SCALE: 1.5:1

INSULATOR: LCP. COLOR: BLACK
 CONTACT: COPPER ALLOY
 WAFER MATERIAL: LCP. COLOR: BLACK
 GUIDE PIN MATERIAL: BRASS
 PICK AND PLACE PAD: COPPER ALLOY

samtec

520 PARK EAST BLVD. NEW ALBANY, IN 47150
 PHONE: 812-944-6733 FAX: 812-948-5047
 e-Mail info@SAMTEC.com code 55322

DESCRIPTION:
2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY

DWG. NO.
HDAM-XX-XX.X-X-13-X-X

BY: D KNOWLDEN 7/15/2005 SHEET 1 OF 2

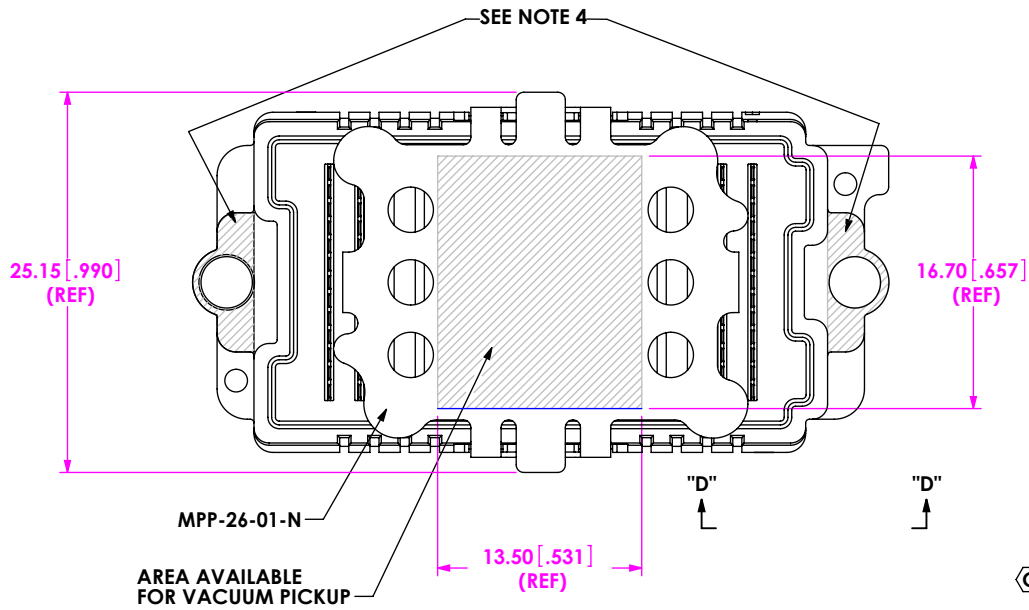
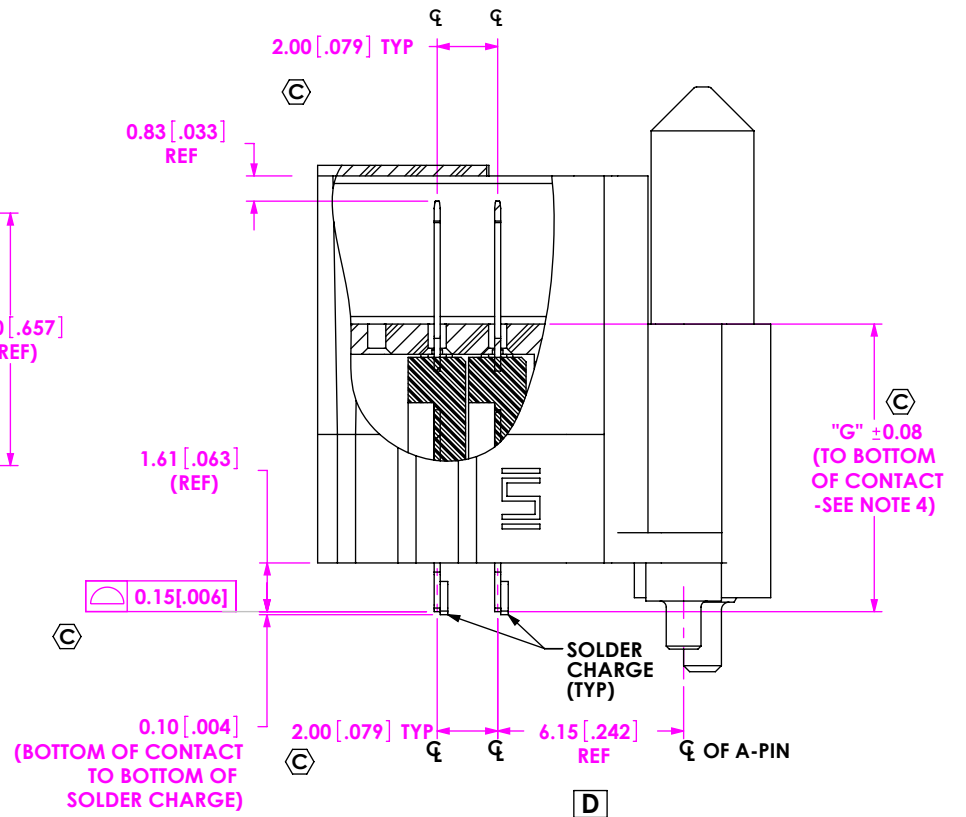
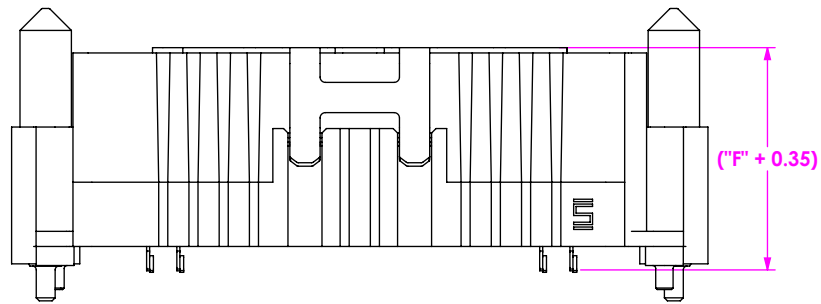


FIG 2
-15: 15 POSITION
(HDAM-15-12.0-X-13-X-P SHOWN)
(SOME WAFERS NOT SHOWN FOR CLARITY)



VIEW D-D
SCALE 4:1

CRITICAL DIMENSION INSPECTION INSTRUCTION TABLE

ASSEMBLY OPERATION	IN-PROCESS INSPECTION
FILL WAFERS	C1, C2, C6, C7, C8, C9, C10, C12, C13
FILL WELD TABS	C3, 10
INSTALL PAD	
FINISHED ASSEMBLY	C13

CPC FREQUENCY THIS SHEET	
A	
B	C13
C	
D	

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DO NOT SCALE DRAWING

SHEET SCALE: 2:1



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PHONE: 812-944-6733 FAX: 812-948-5047
e-Mail info@SAMTEC.com code 55322

DESCRIPTION:
2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY

DWG. NO.
HDAM-XX-XX.X-X-13-X-X

BY:D KNOWLDEN 7/15/2005 SHEET 2 OF 2